

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Eiichi Shinada	06/23/2008
Masahiro Katou	06/23/2008
Noriaki Watanabe	06/23/2008
RECEIVING PARTY DATA	
Name:	Hitachi Chemical Company, Ltd.
Street Address:	1-1, Nishi-Shinjuku 2-chome, Shinjuku-ku,
City:	Tokyo
State/Country:	JAPAN
Postal Code:	163-0449
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12278606
CORRESPONDENCE DATA	
Fax Number:	(703)312-6666
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-312-6600
Email:	rrodriguez@antonelli.com
Correspondent Name:	ANTONELLI, TERRY, STOUT & KRAUS, LLP
Address Line 1:	1300 NORTH SEVENTEENTH STREET
Address Line 2:	SUITE 1800
Address Line 4:	ARLINGTON, VIRGINIA 22209-3873
ATTORNEY DOCKET NUMBER:	648.49073X00
NAME OF SUBMITTER:	William I. Solomon
Total Attachments: 1 source=49073X00ASN#page1.tif	

OP \$40.00 12278606

PATENT

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REEL: 021353 FRAME: 0770

ASSIGNMENT (譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Chemical Company, Ltd., a corporation organized under the laws of Japan, located at 1-1, Nishi-Shinjuku 2-chome, Shinjuku-ku, Tokyo 1630449 Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Chemical Company, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD FOR MANUFACTURING MULTILAYER WIRING BOARD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Chemical Company, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Chemical Company, Ltd.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Eiichi SHINADA</u> <u>Eiichi Shinada</u>	<u>06/23/2008</u>
2)	<u>Masahiro KATOU</u> <u>Masahiro Kato</u>	<u>06/23/2008</u>
3)	<u>Noriaki WATANABE</u> <u>Noriaki Watanabe</u>	<u>06/23/2008</u>
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____